

## **N-Channel Power MOSFET**

40V, 3.9A, 45mΩ

#### FEATURES

- Advance Trench Process Technology
- High density cell design for Ultra Low On-resistance
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

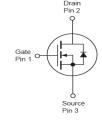
#### APPLICATION

- Load Switch
- Stepper Motors

KEY PERFORMANCE PARAMETERS					
PARA	METER	VALUE	UNIT		
V	DS	40	V		
R <sub>DS(on)</sub> (max)	$V_{GS} = 10V$	45	mΩ		
	$V_{GS} = 4.5V$	62.5			
Qg		10	nC		







Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V <sub>DS</sub>	40	V		
Gate-Source Voltage	V <sub>GS</sub>	±20	V		
Continuous Drain Current (Note 1)	I <sub>D</sub>	3.9	А		
Pulsed Drain Current (Note 2)	I <sub>DM</sub>	16	А		
Total Power Dissipation @ $T_A = 25^{\circ}C$	P <sub>DTOT</sub>	1.25	W		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to +150	°C		

THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction to Case Thermal Resistance	R <sub>eJC</sub>	50	°C/W			
Junction to Ambient Thermal Resistance	R <sub>eja</sub>	100	°C/W			

**Notes:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.  $R_{\Theta JA}$  shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air.





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PARAMETER	CONDITIONS SYMBOL		MIN	ТҮР	MAX	UNIT	
Static (Note 3)			•	•			
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250 \mu A$	BV <sub>DSS</sub>	40			V	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	V <sub>GS(TH)</sub>	1		3	V	
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	nA	
Zero Gate Voltage Drain Current	$V_{DS} = 32V, V_{GS} = 0V$	I <sub>DSS</sub>			1.0	μA	
	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.9A			36	45	6	
Drain-Source On-State Resistance	$V_{GS} = 4.5V, I_D = 3.5A$	R <sub>DS(on)</sub>		50	62.5	mΩ	
Dynamic <sup>(Note 4)</sup>							
Total Gate Charge		Qg		10		nC	
Gate-Source Charge	$V_{DS} = 20V, I_D = 3.9A,$	Q <sub>gs</sub>		1.6			
Gate-Drain Charge	$V_{GS} = 10V$	Q <sub>gd</sub>		2.1			
Input Capacitance		C <sub>iss</sub>		540			
Output Capacitance	$V_{DS} = 20V, V_{GS} = 0V,$	C <sub>oss</sub>		80		pF	
Reverse Transfer Capacitance	f = 1.0MHz	C <sub>rss</sub>		45			
Switching (Note 5)			•	•	•		
Turn-On Delay Time		t <sub>d(on)</sub>		5			
Turn-On Rise Time	$V_{DD} = 20V, R_L = 20\Omega,$	tr		12		- ns	
Turn-Off Delay Time	$I_D = 1A, V_{GEN} = 10V,$	t <sub>d(off)</sub>		20			
Turn-Off Fall Time	$R_{G} = 6\Omega$	t <sub>f</sub>		15			
Source-Drain Diode (Note 3)		1					
Forward On Voltage	I <sub>S</sub> = 1.25A, V <sub>GS</sub> = 0V	V <sub>SD</sub>		0.8	1.2	V	

Notes:

1. Current limited by package

2. Pulse width limited by the maximum junction temperature

3. Pulse test: PW  $\leq$  300µs, duty cycle  $\leq$  2%

4. For DESIGN AID ONLY, not subject to production testing.

5. Switching time is essentially independent of operating temperature.



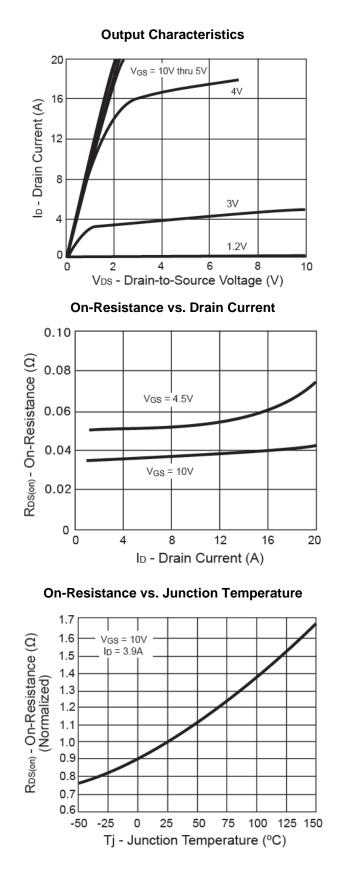
### **ORDERING INFORMATION**

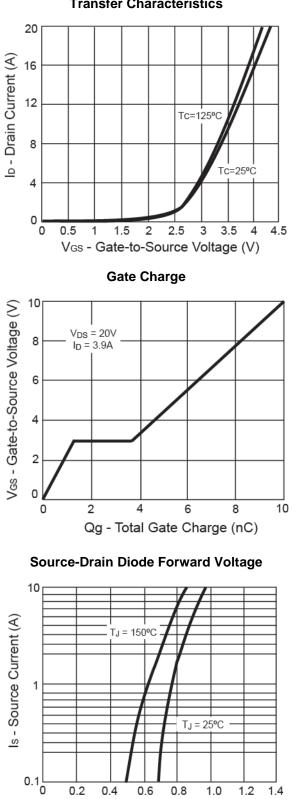
PART NO.	PACKAGE	PACKING
TSM2318CX RFG	SOT-23	3,000pcs / 7" Reel



#### **CHARACTERISTICS CURVES**

 $(T_c = 25^{\circ}C \text{ unless otherwise noted})$ 





#### **Transfer Characteristics**

1.4

1.2

1.0

0.2

0.4

0.6

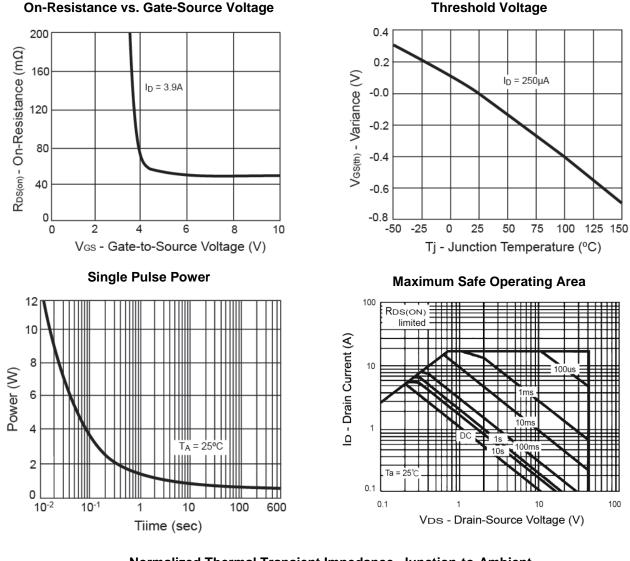
0.8

Vsp - Source-to-Drain Voltage (V)

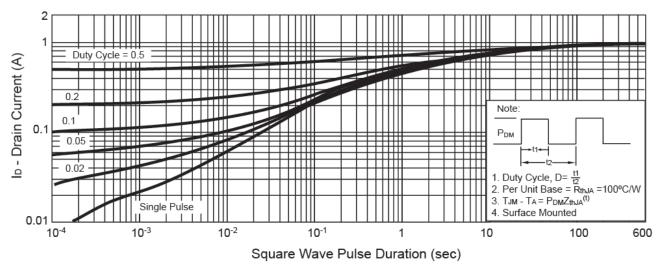


#### **CHARACTERISTICS CURVES**

(Tc = 25°C unless otherwise noted)

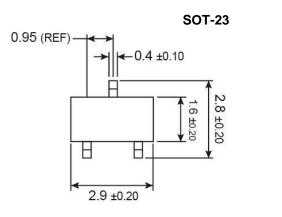


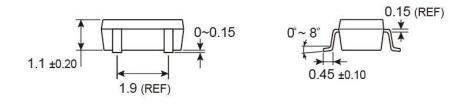




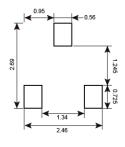


## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

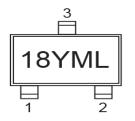




### SUGGESTED PAD LAYOUT



#### **MARKING DIAGRAM**



Y	= Year Code						
Μ	= Month Code	for	Haloge	en Fr	ee Proo	duct	
	<b>O</b> =Jan	Ρ	=Feb	Q	=Mar	R	=Apr
	<b>S</b> =May	т	=Jun	U	=Jul	V	=Aug
	W =Sep	Х	=Oct	Υ	=Nov	Ζ	=Dec
L	= Lot Code (1-	-9,	A~Z)				



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